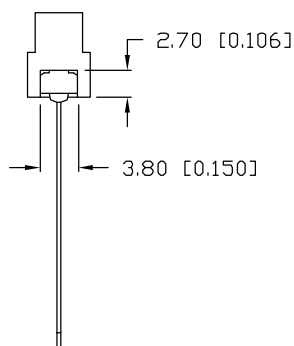
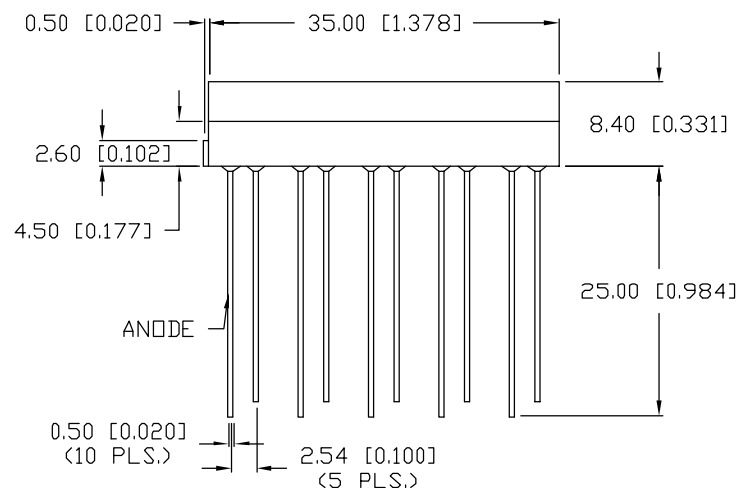
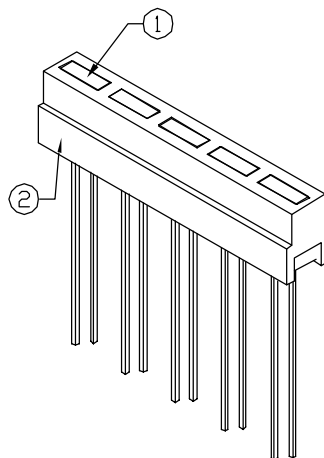
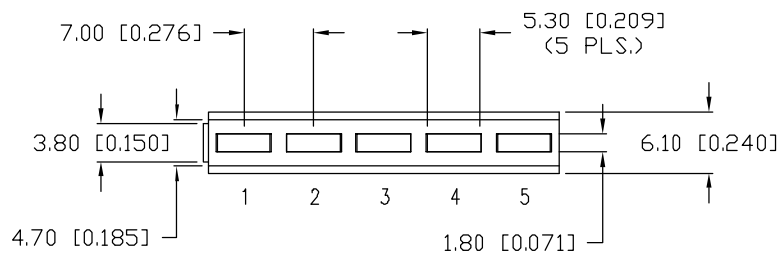


UNCONTROLLED DOCUMENT

PART NUMBER
SSA-LXB525ID

REV.
D



REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	REDRAWN. ADDED B.O.M.	11.25.92
B	REDRAWN. UPDATED SPECS.	5.22.95
C	E.C.N. #10210.	7.17.96
D	E.C.N. #10BRDR. & REDRAWN.	6.4.01

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		12		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		110		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED DIFFUSED				

▣ LIMITS OF SAFE OPERATION AT 25°C PER DIE

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	$\text{mW}/^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

▣ NOTES:

1. SSL-LX2583ID, LED. (5 PCS.)
2. SSH-LXH525, HOLDER.
3. BACKFILL BOTTOM OF HOLDER WITH U.V. GLUE TO SECURE LEDS.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION MAX= +0.00 -DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV. D	PART NUMBER SSA-LXB525ID
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1.8mm x 5.3mm 5 UNIT LED ARRAY,
635nm HIGH INTENSITY RED LEDS, RED DIFFUSED LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT	CHECKED BY:	APPROVED BY:	DATE: 6.27.90
			PAGE: 1 OF 1
			SCALE: N/A